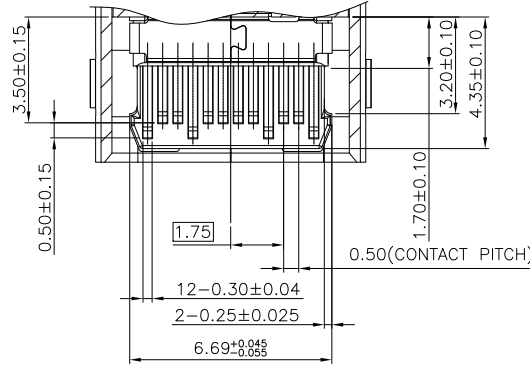
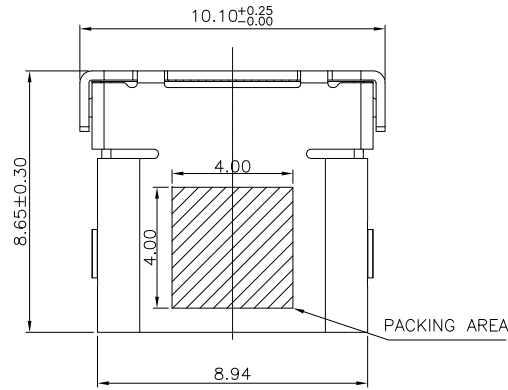
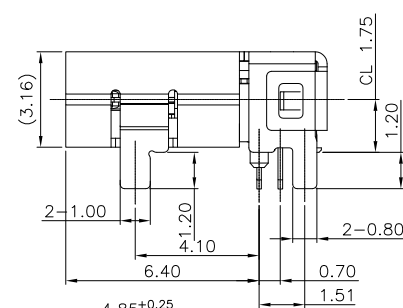
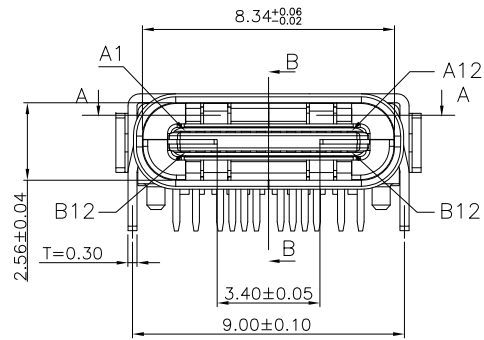


GP Component

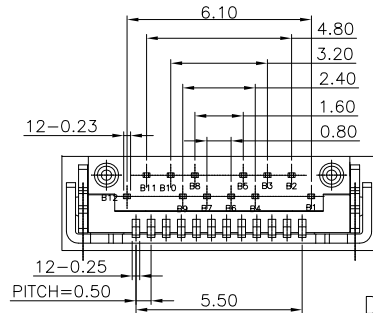
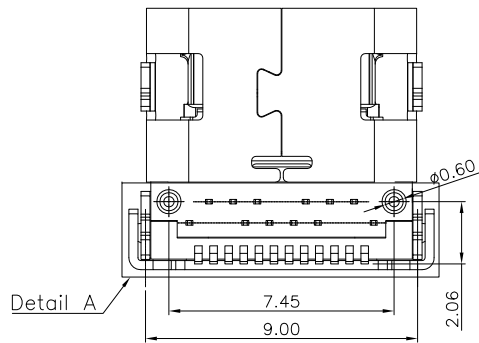
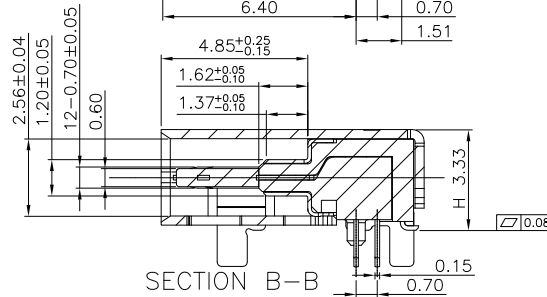
REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
AO			Initial	2017/07/28	Phebe Su



SECTION A-A



SECTION B-B



Detail A

NOTES:

1.MATERIAL:

MOLDING: LCP BLACK UL94 V-0

CONTACT: COPPER ALLOY.

GOLD FLASH PLATED Min ON CONTACT AREA,
100u" Min TIN (LEAD FREE) ON SOLDER AREA,

SHELL: SUS304-H,T=0.30±0.03mm

50u" NICKEL PLATING OVER ALL.

SHILD: SUS304-H,T=0.12±0.03mm

2.MECHANICAL:

INSERTION: 5~20N.

EXTRACTION: 8~20N AFTER TEST.

DURABILITY: 10000 CYCLES

3.ELECTRICAL:

CURRENT: 5A FOR VBUS;

1.25A FOR GND PIN.

0.25A FOR OTHER.

VOLTAGE: 20 V MAX

WITHSTANDING VOLTAGE: 100V AC R.M.S.

CONTACT RESISTANCE: 40mΩ MAX.

INSULATION RESISTANCE: 100MΩ MIN.

4.ENVIRONMENTAL

TEMPERATURE RANGE -40°C ~ +85°C

MATRIX PART NO:

MUSB12-01-241

MATRIX USB

Series number

Pin Number

Plating
01:Gold Flash
15:15u"
30:30u"



Matrix Electronics Co.,Ltd

TOLERANCE: X.X ±0.25 X.XX ±0.15 X.XXX ±0.05 ANGLE: ±3°	DESIGN BY : Phebe Su	DATE : 2017/07/28	PART NAME: USB 3.1 Type C Gen 2 Female R/A, CL 1.75	
	CHECKED BY: Vicky Hsieh	DATE : 2017/07/28	PART NO.	MUSB12-01-241
 UNIT: mm [inch]	APPROVED BY1: Richard Hsieh	DATE : 2017/07/28	MOLD NO.	NA
	SCALE:1:1 SIZE:A4	APPROVED BY2: Richard Hsieh	DATE : 2017/07/28	DRAW NO. SHEET NO.